

WHAT IS CLAIMED IS:

1. A method for adjusting the number of wafers, comprising the steps of:  
determining an excluding wafer comprising at least one semiconductor wafer to be excluded from a given lot composed of plurality of semiconductor wafers; and  
after excluding the excluding wafer from the given lot, performing a given process among a plurality of processes for fabrication of a semiconductor device for the remaining semiconductor wafers in the given lot,  
wherein the step of determining an excluding wafer includes determining the excluding wafer based on a yield of a lot that has completed the plurality of processes and processing results of an upstream process among the plurality of processes performed for the plurality of semiconductor wafers prior to the given process.
2. The method of Claim 1, wherein the step of determining an excluding wafer includes calculating the number of excluding wafers based on the yield and determining as the excluding wafer a semiconductor wafer of the quantity equal to the calculated number of excluding wafers that has processing results largely deviated from a target value of the processing results of the upstream process.